

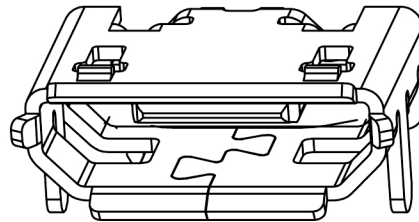
7.50 [0.295]

4.85 [0.191]

0.35 [0.014]±0.05

7.20 [0.283]

0.10



1.00 [0.039](4X)

2.85 [0.112]

0.90 [0.035]

2.20 [0.087]

3.00 [0.118]Ref.

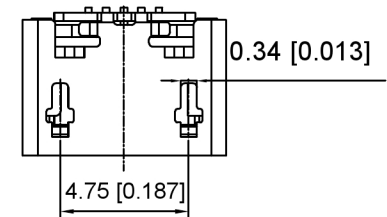
2.60 [0.102]

1.30 [0.051]

0.25 [0.010]±0.05

0.27 [0.011]

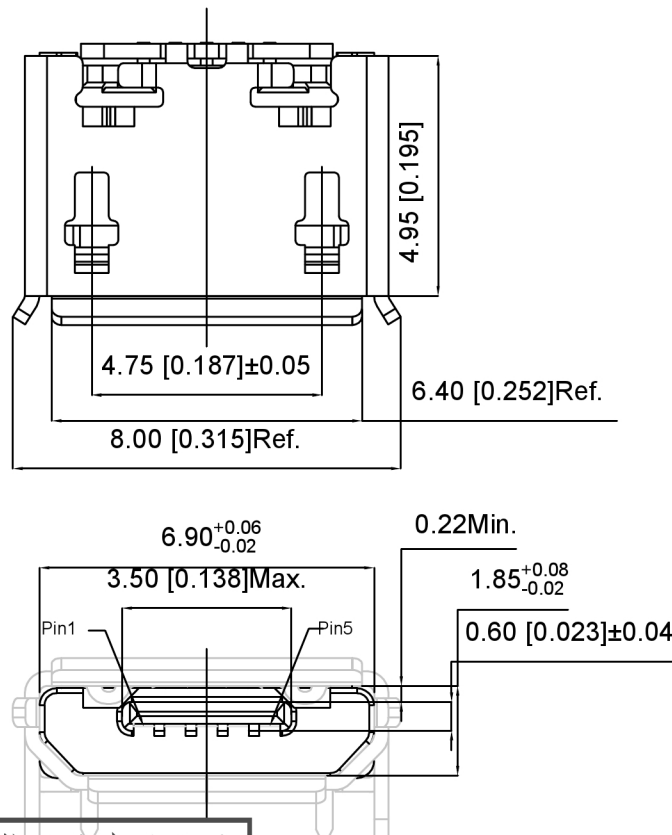
0.59 [0.023]Ref.



Flat(F)

- NOTE:
- 1.MATERIAL SPECIFICATION:
1.HOUSING:LCP,UL94 V-0 BLACK.
2.CONTACTS: BRASS(C2680 T=0.15)
3.FRONT SHELL: STAINLESS STEEL(SUS304 T=0.3)
 - 2.PLATING SPECIFICATION:
2-1.CONTACTS:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW:
2-2.FRONT SHELL:
SEE TABLE 1.
50u" MIN. NICKEL UNDER PLATING OVER ALL.
 - 3.MECHANICAL PERFORMANCE,
3-1.INSERTION FORCE: 3.5Kgf MAX
3-2.REMOVAL FORCE: 0.8kgf MIN
3-3.DURABILITY: 10000 CYCLES.
 - 4.ELECTRICAL PERFORMANCE,
4-1.CURRENT RATING:
VBUS & GND PINS: 1.8A MAX.
OTHER PINS: 0.5A MAX.
4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 30mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
4-3.INSULATION RESISTANCE: 100MΩ MIN
4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
 5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25°C~+85°C.
 - 6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

U254-05XX-4BH23-X2S
1:AU 1U"
6:AU 30U"
T:TIN
N:NICKEL
S:Sus
2:WITHOUT
S:Scrolls F:Flat

6.90^{+0.06}_{-0.02}

0.22Min.

3.50 [0.138]Max.

1.85^{+0.08}_{-0.02}

0.60 [0.023]±0.04

Pin1

Pin5

广东星坤科技股份有限公司

审核	日期

文件工程章

DESCRIPTION

DATE

REVISED

APPROVED

REVISIONS

www.helloxkb.com www.helloxkb.cn www.xk-dg.cn

UNSPECIFIED TOLERANCES

ANGULAR	±5°
L ≤ 4	±0.2
4 < L ≤ 16	±0.3
16 < L ≤ 63	±0.4
L > 63	±0.5

XKB

XKB INDUSTRIAL PRECISION CO.,LIMITED

DSND		SCALE: N/A	MODEL TYPE: MICRO USB
DWN		VIEW:	PART NO.: U254-05XX-4BH23-X2S
CHKD		UNIT: mm/in	DWG NO.:
APPD		SIZE: A4	
			WEIGHT
			SHEET
			REVISIC
			1/1
			A0